

This Page Is Inserted by IFW Operations
and is not a part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

IMAGES ARE BEST AVAILABLE COPY.

**As rescanning documents *will not* correct images,
please do not report the images to the
Image Problem Mailbox.**

ABSTRACT OF THE DISCLOSURE

To form through electrodes effectively without deteriorating the quality of the through

~~electrodes.~~ electrodes, a semiconductor substrate-1 is spin etched at its back surface-1", thereby thinning down the semiconductor substrate-1, making opening sections-3 penetrate the semiconductor substrate-1, and forming through holes-3 in the semiconductor substrate-1. Tips of embedded electrodes-7 are exposed out of the through holes-3 in the semiconductor substrate-1, to form through electrodes-7'.